



### Dual N-channel 30 V, 0.017 Ω typ., 8 A, STripFET™ II Power MOSFET in a SO-8 package

Datasheet - production data

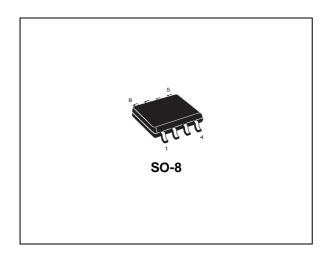
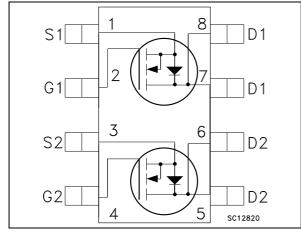


Figure 1. Internal schematic diagram



#### **Features**

Order code	V <sub>DS</sub>	R <sub>DS(on)</sub> max	I <sub>D</sub>
STS8DNF3LL	30 V	0.020 Ω	8 A

- Optimal R<sub>DS(on)</sub> x Q<sub>g</sub> trade-off @ 4.5 V
- · Conduction losses reduced
- Switching losses reduced

### **Applications**

· Switching applications

### **Description**

This Power MOSFET has been developed using STMicroelectronics' unique STripFET process, which is specifically designed to minimize input capacitance and gate charge. This renders the device suitable for use as primary switch in advanced high-efficiency isolated DC-DC converters for telecom and computer applications, and applications with low gate charge driving requirements.

**Table 1. Device summary** 

Order code	Order code Marking		Packaging
STS8DNF3LL	8DF3LL	SO-8	Tape and reel

Contents STS8DNF3LL

### **Contents**

1	Electrical ratings
2	Electrical characteristics
3	Test circuit 8
4	Package mechanical data
5	Packaging mechanical data11
6	Revision history

STS8DNF3LL Electrical ratings

# 1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V <sub>DS</sub>	Drain-source voltage	30	V
V <sub>GS</sub>	Gate- source voltage	±16	V
I <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 25 °C single operating	8	Α
I <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 100 °C single operating	5	Α
I <sub>DM</sub> <sup>(1)</sup>	Drain current (pulsed)	32	Α
P <sub>TOT</sub>	Total dissipation at $T_C$ = 25 °C dual operating Total dissipation at $T_C$ = 25 °C single operating	2 1.6	W W

<sup>1.</sup> Pulse width limited by safe operating area

Table 3. Thermal data

Symbol	Parameter	Value	Unit
R <sub>thj-amb</sub> <sup>(1)</sup>	Thermal resistance junction-ambient single operating	78	°C/W
· ·tnj-amb	Thermal resistance junction-ambient dual operating	62.5	°C/W
$T_J$	Thermal operating junction-ambient	150	°C
T <sub>stg</sub>	Storage temperature	-55 to 150	°C

<sup>1.</sup> Mounted on FR-4 board with 0.5 in<sup>2</sup> pad of Cu

Electrical characteristics STS8DNF3LL

### 2 Electrical characteristics

(T<sub>CASE</sub>=25°C unless otherwise specified)

Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source Breakdown voltage	$I_D = 250 \mu\text{A},  V_{GS} = 0$	30			V
1	Zero gate voltage	V <sub>DS</sub> = 30 V			1	μΑ
I <sub>DSS</sub>	Drain current (V <sub>GS</sub> = 0)	V <sub>DS</sub> =30 V, T <sub>C</sub> =125°C			10	μΑ
I <sub>GSS</sub>	Gate-body leakage current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ± 16 V			±100	nA
V <sub>GS(th)</sub>	Gate threshold voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1			V
R <sub>DS(on)</sub>	Static drain-source on- resistance	$V_{GS} = 10 \text{ V}, I_D = 4 \text{ A}$ $V_{GS} = 4.5 \text{ V}, I_D = 4 \text{ A}$		0.017 0.020	0.020 0.024	W W

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
9 <sub>fs</sub> <sup>(1)</sup>	Forward transconductance	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 4 A	-	12.5		S
C <sub>iss</sub>	Input capacitance		-	800		pF
Coss	Output capacitance	$V_{DS} = 25 \text{ V, f} = 1 \text{ MHz,}$	-	250		pF
C <sub>rss</sub>	Reverse transfer capacitance	V <sub>GS</sub> = 0	-	60		pF
Qg	Total gate charge	V <sub>DD</sub> = 15 V, I <sub>D</sub> = 8 A,	-	12.5	17	nC
Q <sub>gs</sub>	Gate-source charge	V <sub>GS</sub> = 5 V	-	3.2		nC
Q <sub>gd</sub>	Gate-drain charge	(see Figure 15)	-	4.5		nC

<sup>1.</sup> Pulsed: Pulse duration = 300  $\mu$ s, duty cycle 1.5.

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t <sub>d(on)</sub>	Turn-on delay time	V <sub>DD</sub> =15 V, I <sub>D</sub> =4 A,	-	18	-	ns
t <sub>r</sub>	Rise time	$R_G=4.7\Omega$ , $V_{GS}=4.5V$ (see <i>Figure 14</i> )	-	32	-	ns
t <sub>d(off)</sub>	Turn-off delay time	V <sub>DD</sub> =15 V, I <sub>D</sub> =4A,	-	21	-	ns
t <sub>f</sub>	Fall time	$R_G$ =4.7 $\Omega$ , $V_{GS}$ = 4.5 $V$ (see <i>Figure 14</i> )	-	11	-	ns

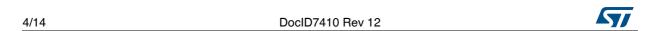


Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Тур.	Max	Unit
I <sub>SD</sub>	Source-drain current		-		8	Α
I <sub>SDM</sub> <sup>(1)</sup>	Source-drain current (pulsed)		-		32	Α
V <sub>SD</sub> <sup>(2)</sup>	Forward on voltage	I <sub>SD</sub> = 8 A, V <sub>GS</sub> = 0	-		1.2	V
t <sub>rr</sub> Q <sub>rr</sub> I <sub>RRM</sub>	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD} = 8 \text{ A}, V_{DD} = 15 \text{ V}$ di/dt = 100 A/ $\mu$ s, $T_j = 150 ^{\circ}\text{C}$ (see <i>Figure 16</i> )	-	23 17 1.5		ns nC A

<sup>1.</sup> Pulse width limited by safe operating area.

<sup>2.</sup> Pulsed: Pulse duration = 300  $\mu$ s, duty cycle 1.5%

**Electrical characteristics** STS8DNF3LL

#### **Electrical characteristics (curves)** 2.1

Figure 2. Safe operating area

lo(A) 10<sup>1</sup>,

Figure 3. Thermal impedance

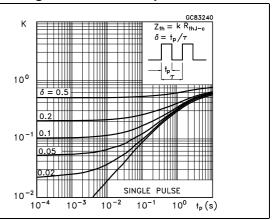


Figure 4. Output characteristics

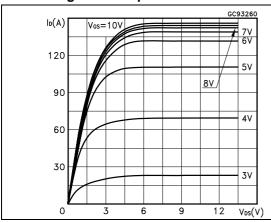


Figure 5. Transfer characteristics

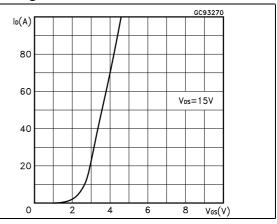


Figure 6. Transconductance

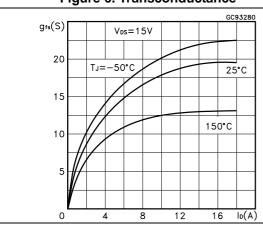
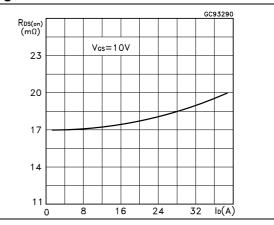


Figure 7. Static drain-source on-resistance



DocID7410 Rev 12 6/14

Figure 8. Gate charge vs. gate-source voltage

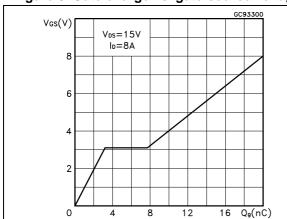


Figure 9. Capacitance variations

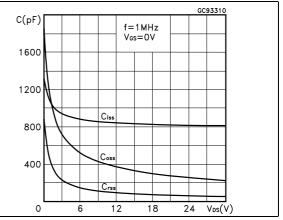


Figure 10. Normalized gate threshold voltage vs. temperature

Figure 11. Normalized on-resistance vs. temperature

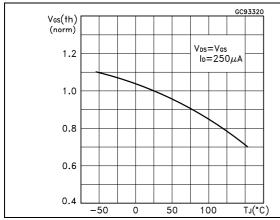
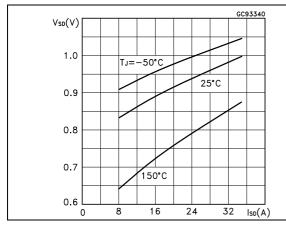
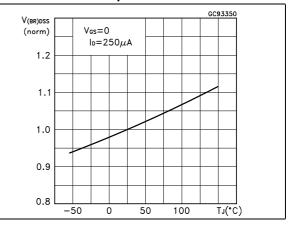


Figure 12. Source-drain diode forward characteristics

Figure 13. Normalized breakdown voltage vs. temperature





Test circuit STS8DNF3LL

### 3 Test circuit

Figure 14. Switching times test circuit for resistive load

Figure 15. Gate charge test circuit

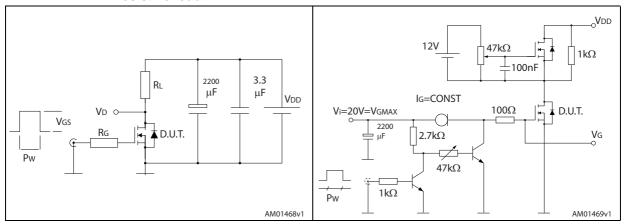


Figure 16. Test circuit for inductive load switching and diode recovery times

Figure 17. Unclamped Inductive load test circuit

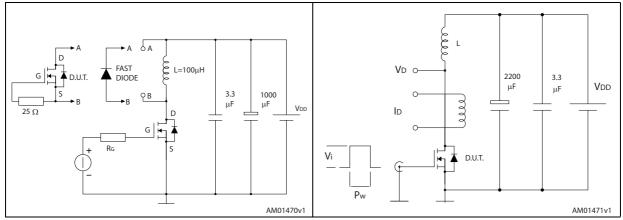
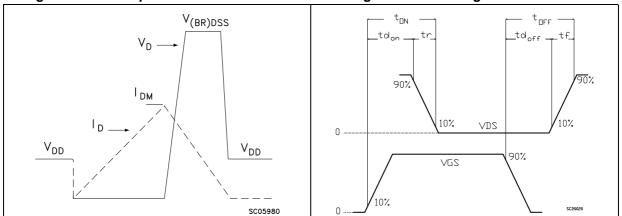


Figure 18. Unclamped inductive waveform

Figure 19. Switching time waveform



57

## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: <a href="https://www.st.com">www.st.com</a>. ECOPACK<sup>®</sup> is an ST trademark.

Table 8. SO-8 mechanical data

Dim		mm	
Dim.	Min.	Тур.	Max.
А			1.75
A1	0.10		0.25
A2	1.25		
b	0.31		0.51
b1	0.28		0.48
С	0.10		0.25
c1	0.10		0.23
D	4.80	4.90	5.00
Е	5.80	6.00	6.20
E1	3.80	3.90	4.00
е		1.27	
h	0.25		0.50
L	0.40		1.27
L1		1.04	
L2		0.25	
k	0°		8°
ccc			0.10



SECTION B-B

SECTION B-B

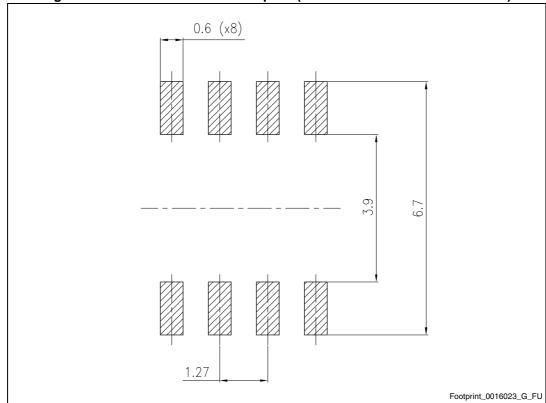
SECTION B-B

D

OU16023\_G\_FU

Figure 20. SO-8 drawing





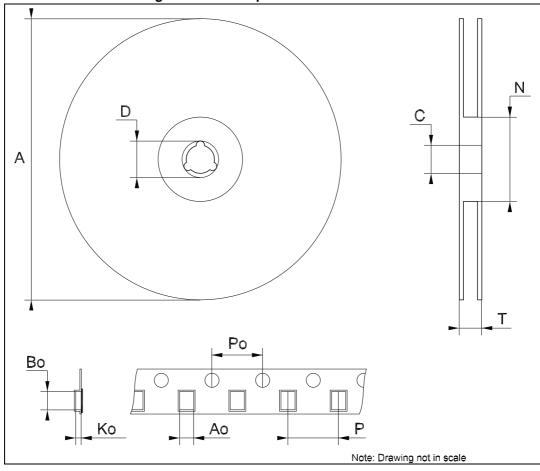
57

# 5 Packaging mechanical data

Table 9. SO-8 tape and reel mechanical data

Dim		mm	
Dim.	Min.	Тур.	Max.
Α			330
С	12.8		13.2
D	20.2		
N	60		
Т			22.4
Ao	8.1		8.5
Во	5.5		5.9
Ko	2.1		2.3
Ро	3.9		4.1
Р	7.9		8.1





DocID7410 Rev 12

Figure 22. SO-8 tape and reel dimensions

**\7**/

STS8DNF3LL Revision history

# 6 Revision history

Table 10. Revision history

Date	Revision	Changes
11-Sep-2006	8	Complete document
15-Nov-2006	9	The document has been reformatted
30-Jan-2007	10	Typo mistake on Table 2
14-Dec-2012	11	- Typo mistake on <i>Table 2</i> - Updated: <i>Section 4: Package mechanical data</i>
22-Jul-2013	12	<ul><li>Updated <i>Table 1: Device summary</i>.</li><li>Minor text changes.</li></ul>

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14/14 DocID7410 Rev 12

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